



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
James A. McCall et al.  
Application No.: 09/911,752  
Filed: July 23, 2001  
For: SYSTEMS HAVING MODULES WITH  
BUFFER CHIPS

---

) Examiner: Tuan T. Dinh  
)  
Art Unit: 2827

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231 on:

12-30-02

Date of Deposit

Derek S. Watson

Name of Person Mailing Correspondence

S. S. C. 12-30-02

Signature      Date

Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT

Sir:

This is in response to the Office action dated October 1, 2002. Reconsideration of the application is requested.

ENTIRE SET OF PENDING CLAIMS (Clean version)

1. (Amended) A system comprising:  
first and second modules, the first module having a first group of chips and the second module having a second group of chips;  
a circuit board including first and second module connectors to receive the first and second modules, respectively;  
a first buffer on the first module and a second buffer on the second module; and  
a path including conductors in a first section that splits into a second section and third section, wherein the second section couples to the first buffer and the third section couples to the